FORMING SOLDER BUMPS ON SEMICONDUCTOR CHIPS

ABSTRACT

A method of providing solder bumps on terminal pads of an integrated circuit flip chip using a carrier substrate which includes wells. The wells are filled with a solder paste and the chip then contacted with the carrier such that its terminal pads register with the paste in the wells. The terminal pads are solder wettable whereas the wells are not. Thus on reflowing the solder it adheres to the terminal pads and withdraws from the wells, and coalesces into bumps on the terminal pads. The chip is then removed from the carrier substrate which can be recycled for bumping a subsequent batch of chips.

(No figure to accompany the abstract)